

WAFER-LEVEL ELECTRONIC MODULES WITH INTEGRAL CONNECTOR CONTACTS AND METHODS OF FABRICATING THE SAME

ABSTRACT OF THE DISCLOSURE

An electronic module comprises a monolithic microelectronic substrate including at least one integrated circuit die, e.g., a plurality of unseparated memory dice or a mixture of different types of integrated circuit dice. The monolithic substrate further includes a redistribution structure disposed on the at least one integrated circuit die and providing a connector contact coupled to the at least one integrated circuit die. For example, the connector contact may be configured as edge connector contact for the module. The redistribution structure may be configured to provide a passive electronic device, e.g., an inductor, capacitor and/or resistor, electrically coupled to the at least one integrated circuit die and/or the redistribution structure may comprise at least one conductive layer configured to provide electrical connection to a contact pad of an electronic device mounted on the substrate. Methods of fabricating electronic modules are also discussed.